

A perspective view of a multi-layered electronic device assembly. The assembly includes a top layer 100, which is a substrate or cover. Below it are several layers and components. A central component 200 is shown with various features labeled: 202, 204, 206, 208, 210, 212, 214, 216, 218, 220, 222, 224, 226, 228, 230, 232, 234, 236, 238, 240, 242, 244, 246, 248, 250, 252, 254, 256, 258, 260, 262, 264, 266, 268, 270, 272, 274, 276, 278, 280, 282, 284, 286, 288, 290, 292, 294, 296, 298, 300. Other components include 120, 122, 124, 126, 128, 130, 132, 134, 136, 138, 140, 142, 144, 146, 148, 150, 152, 154, 156, 158, 160, 162, 164, 166, 168, 170, 172, 174, 176, 178, 180, 182, 184, 186, 188, 190, 192, 194, 196, 198, 200. The diagram shows a complex arrangement of layers and components, likely representing a semiconductor device or a similar electronic assembly.

Replacement Sheet

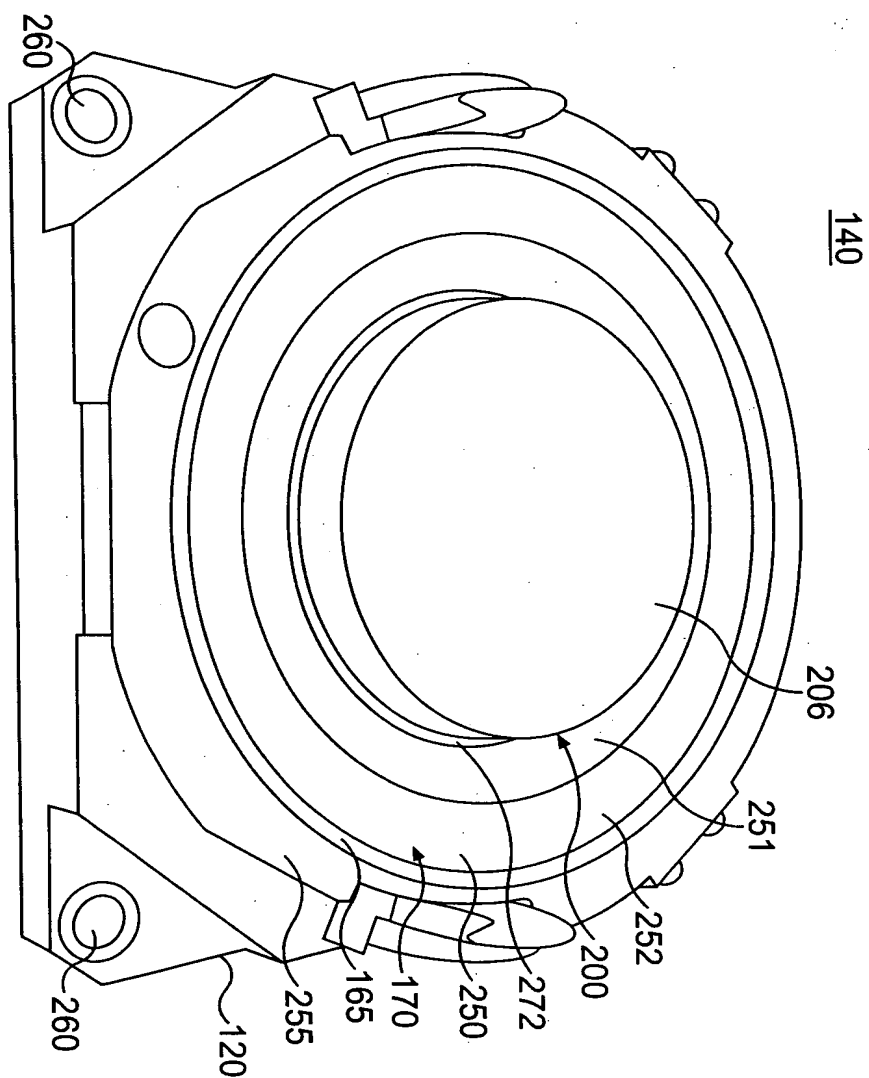
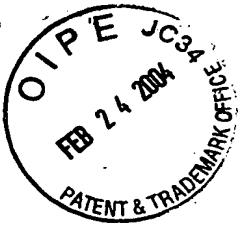


FIG. 2a



140

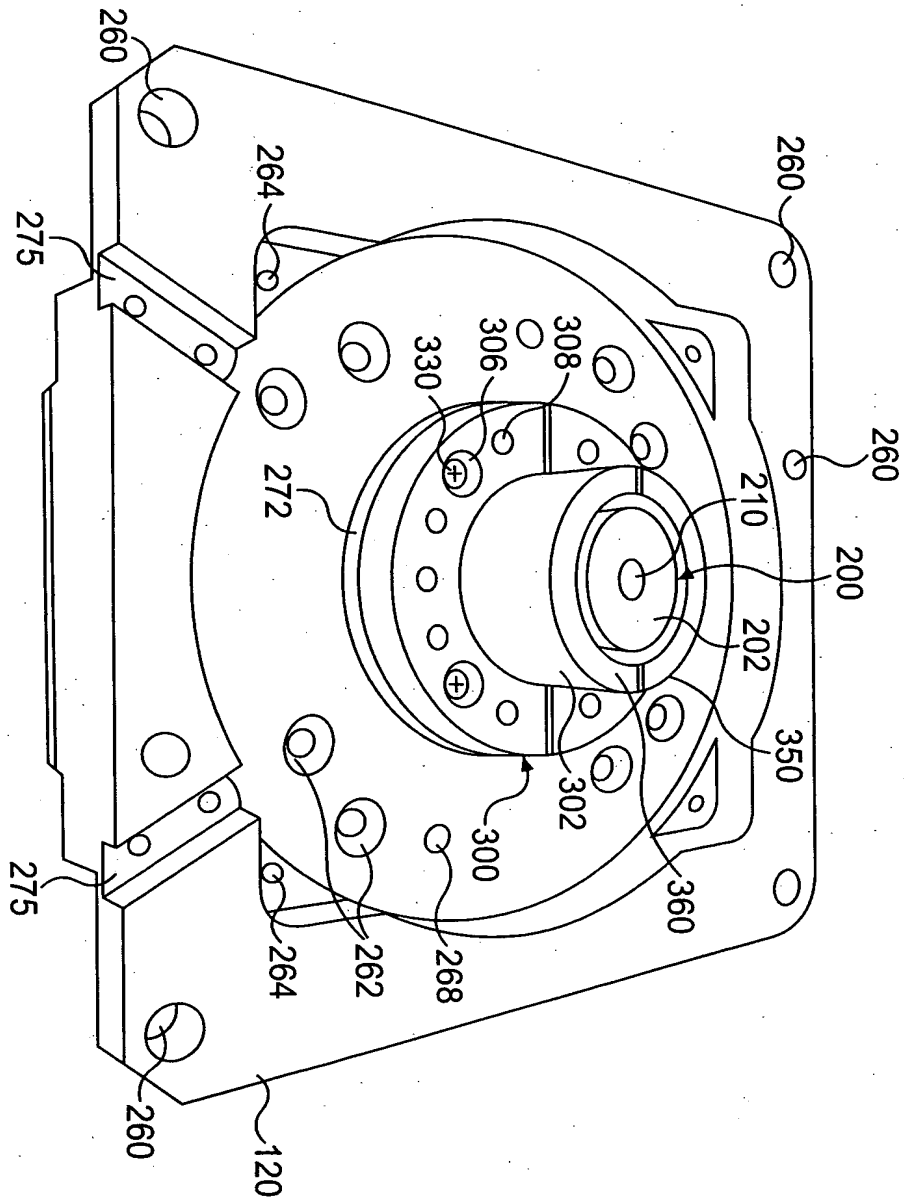
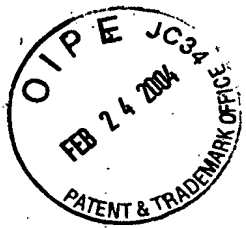
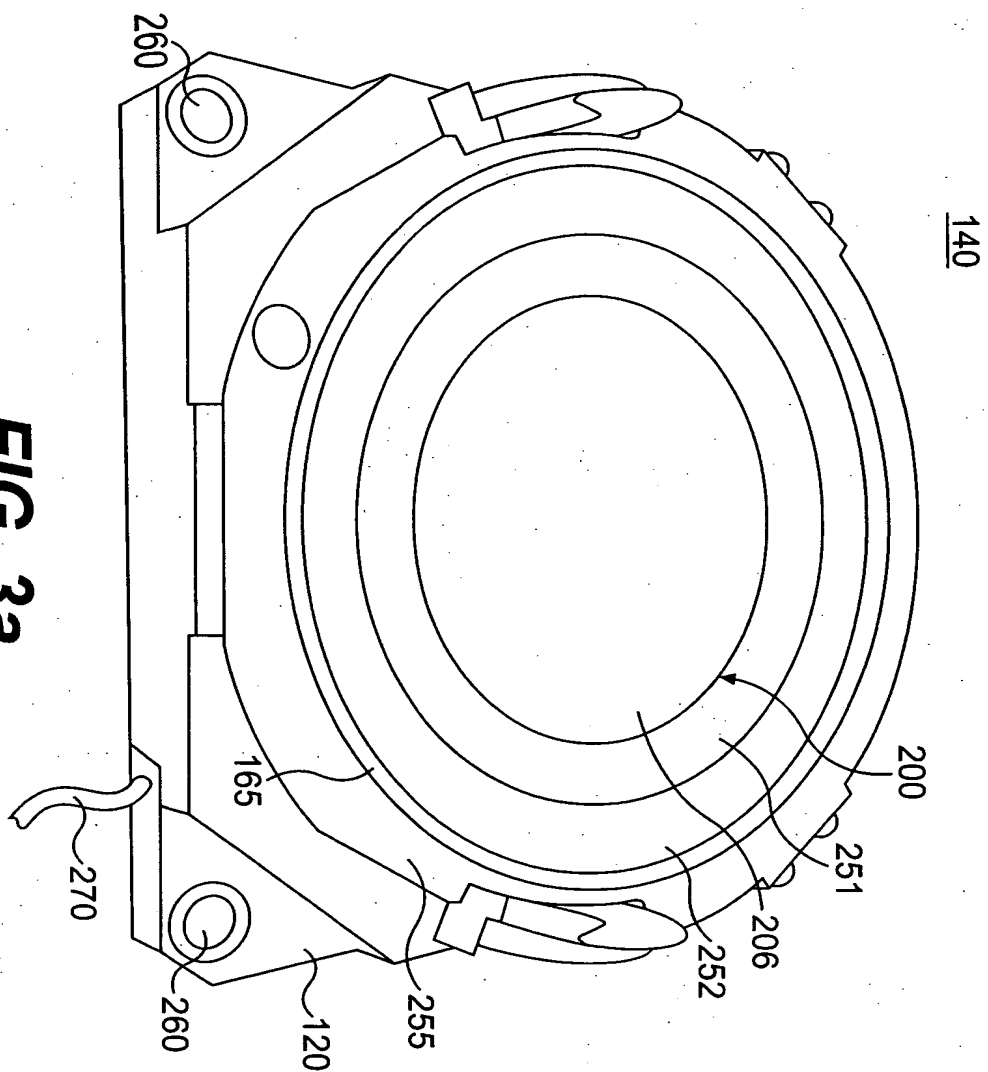


FIG. 2b



Replacement Sheet



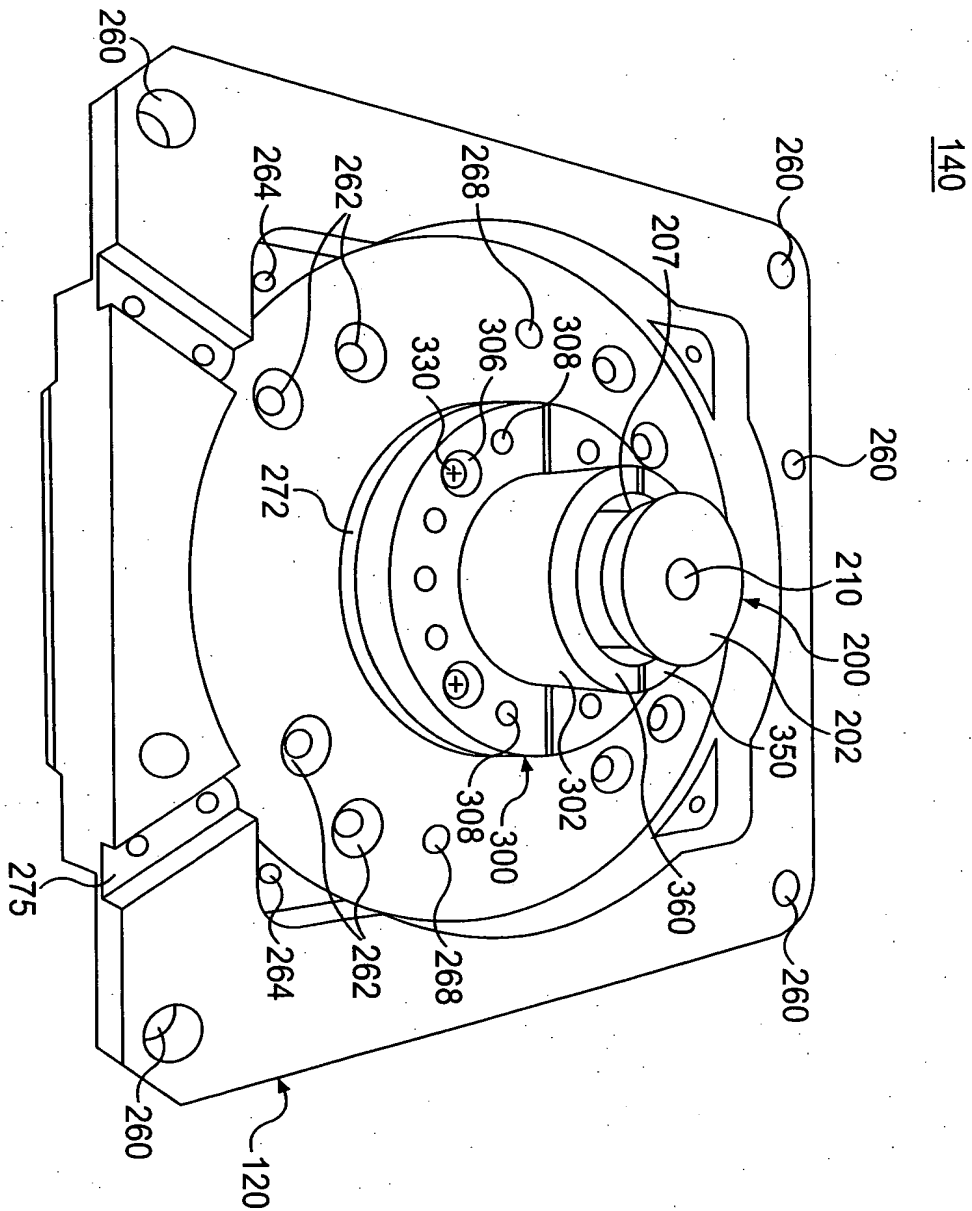


FIG. 3b

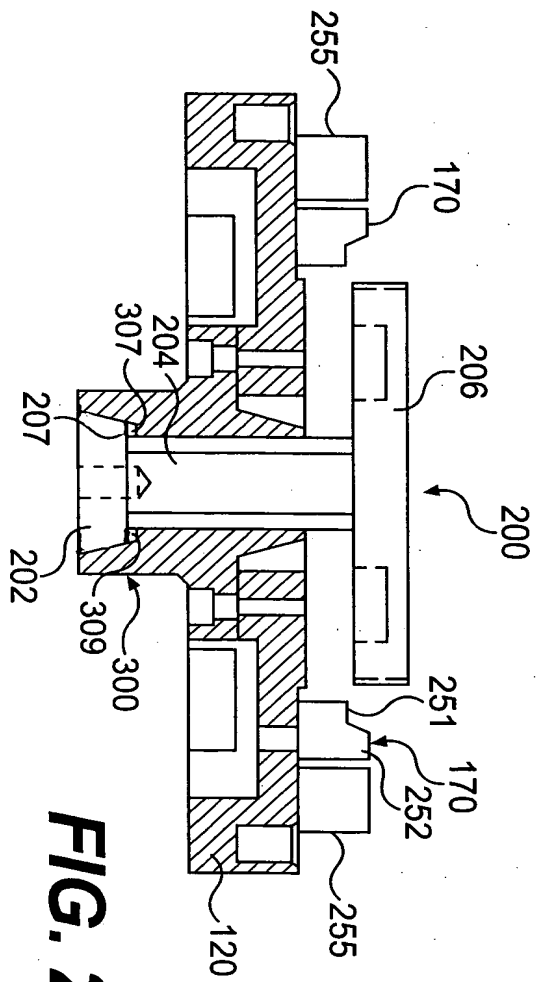


FIG. 2c

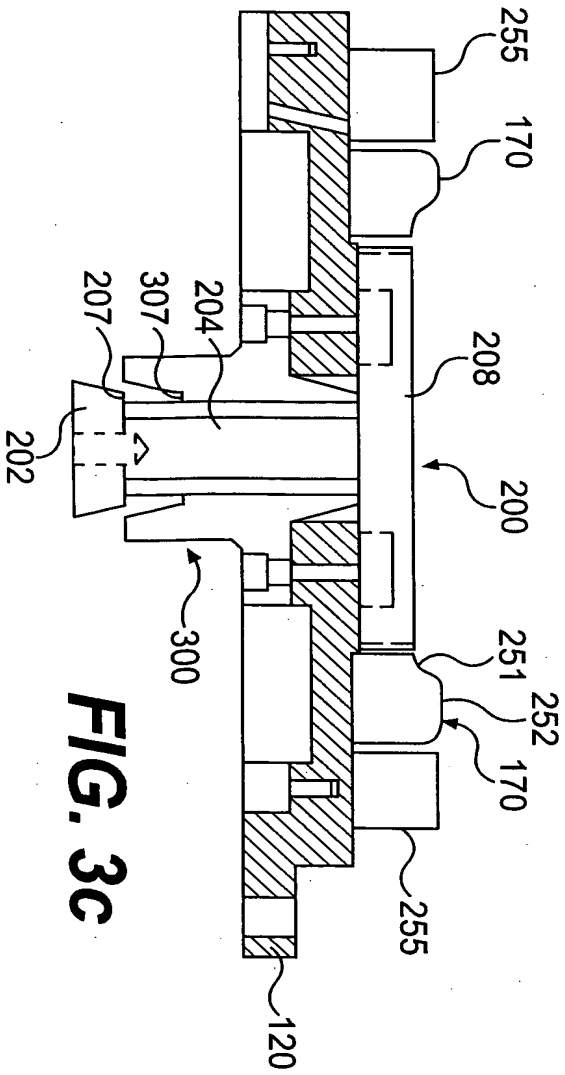


FIG. 3c

FIG. 4a

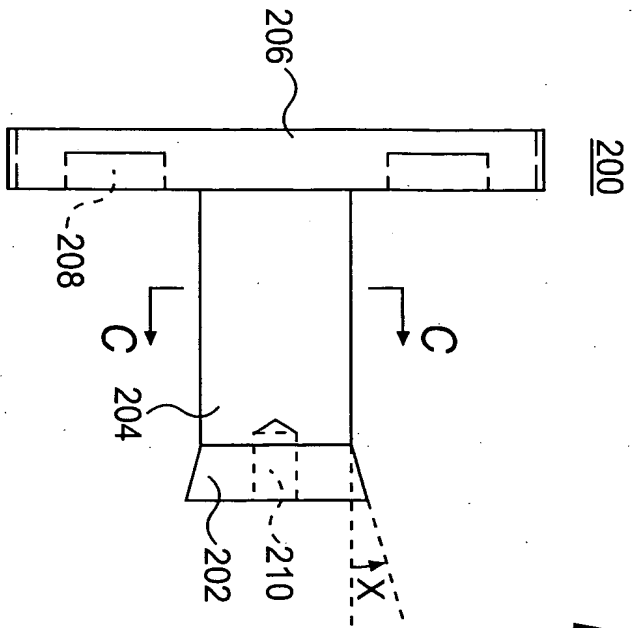


FIG. 4c

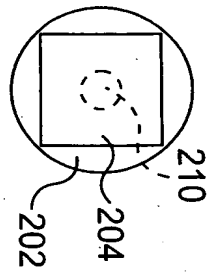
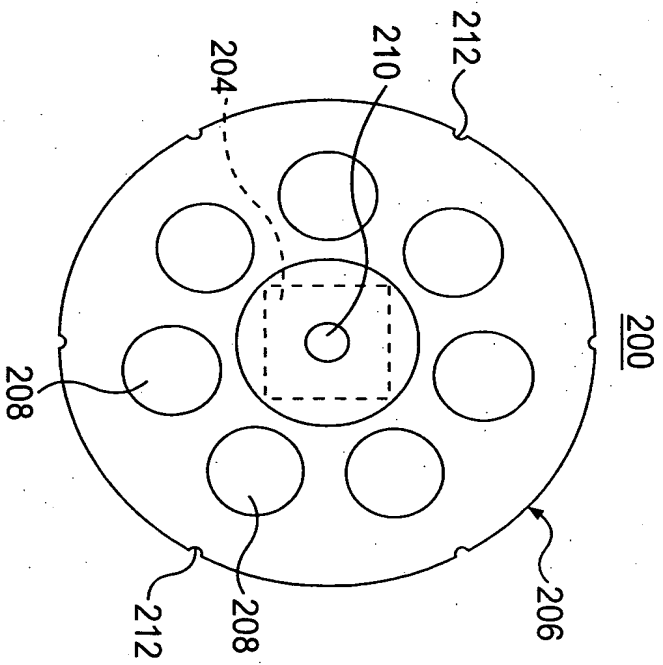
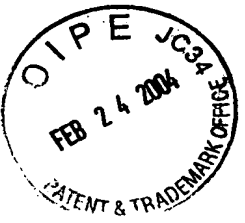


FIG. 4b





Replacement Sheet

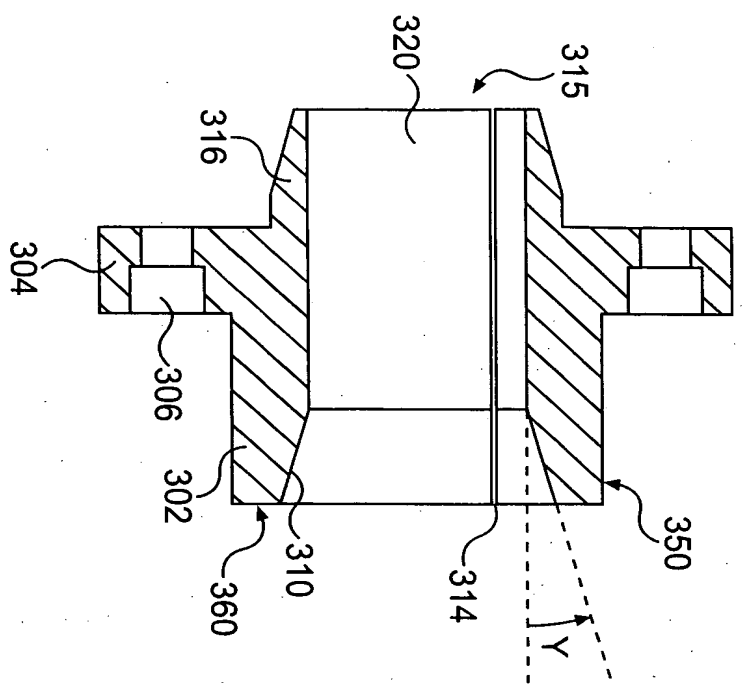


FIG. 5a

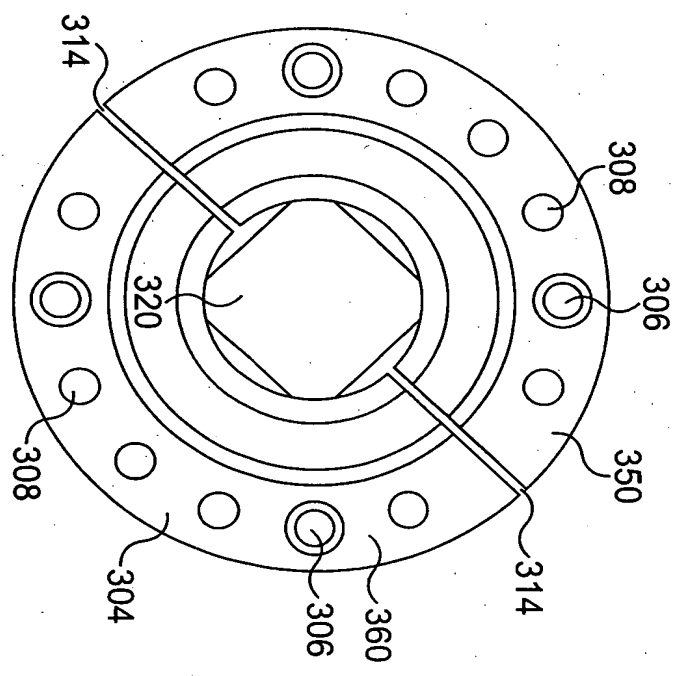
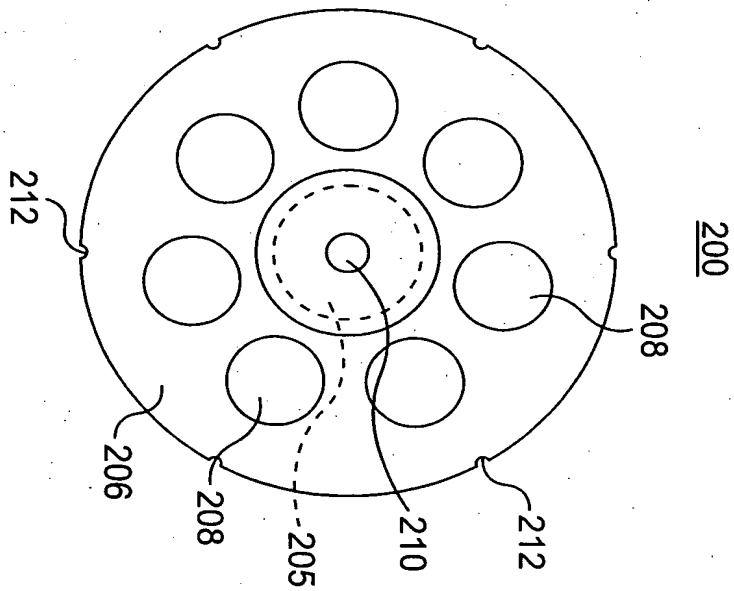
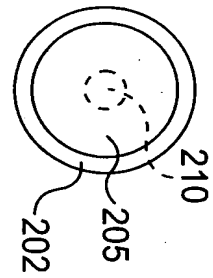
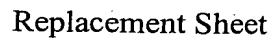


FIG. 5b



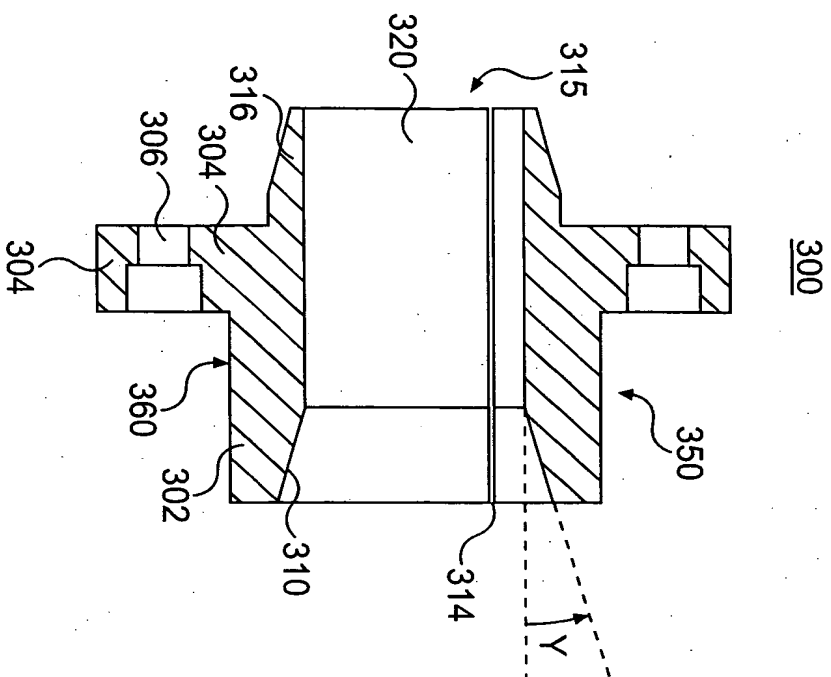


FIG. 7a

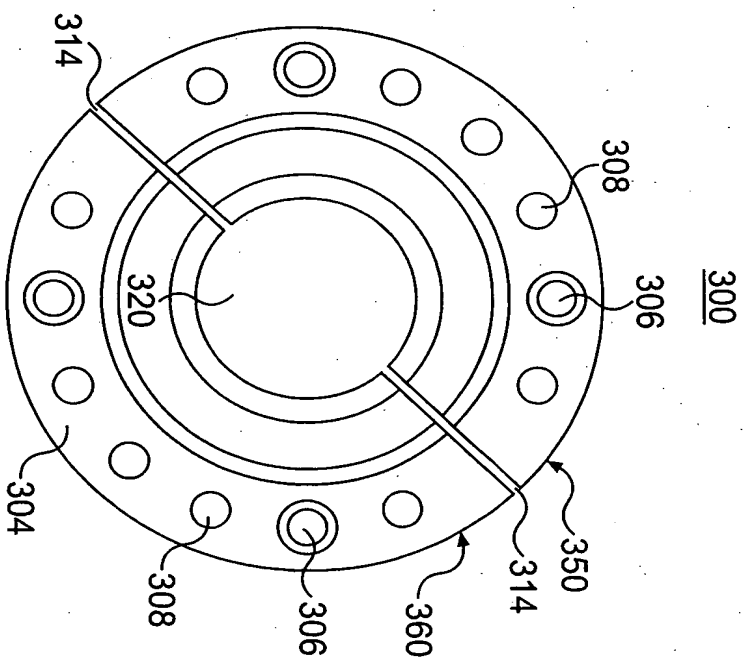


FIG. 7b

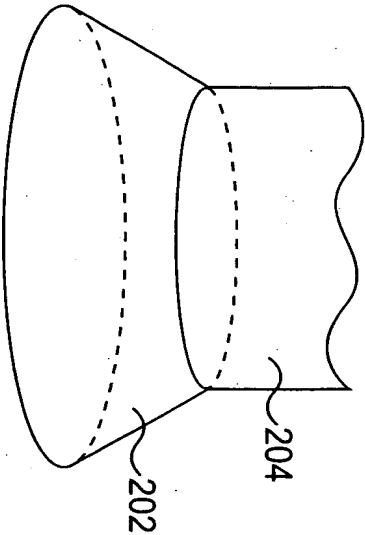
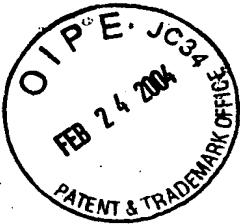


FIG. 8a

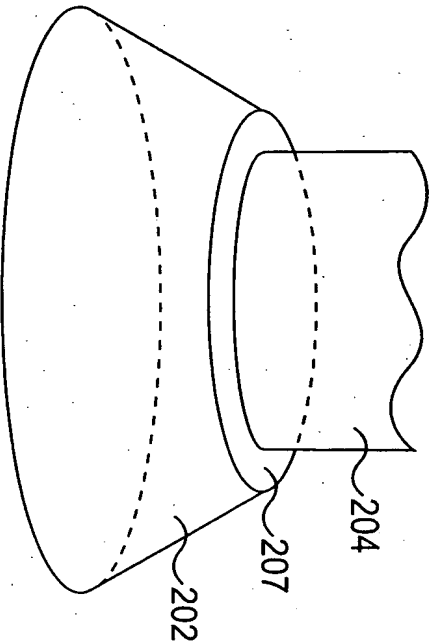


FIG. 8b

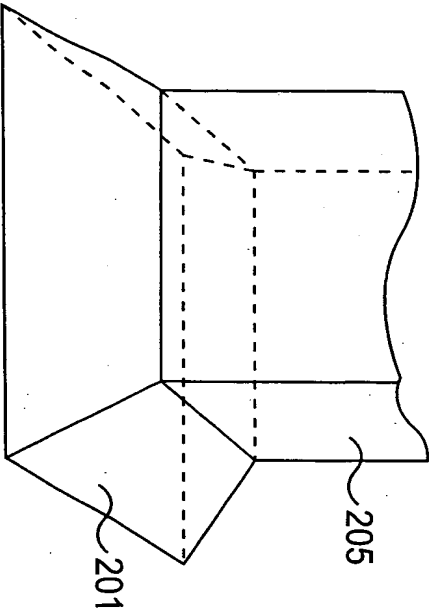


FIG. 8c

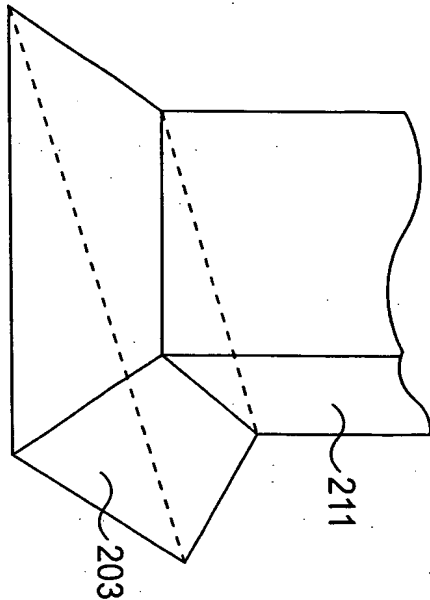


FIG. 8d

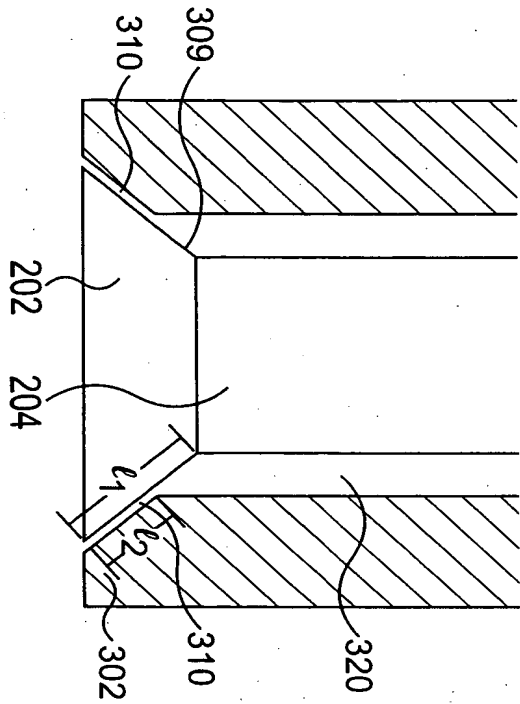
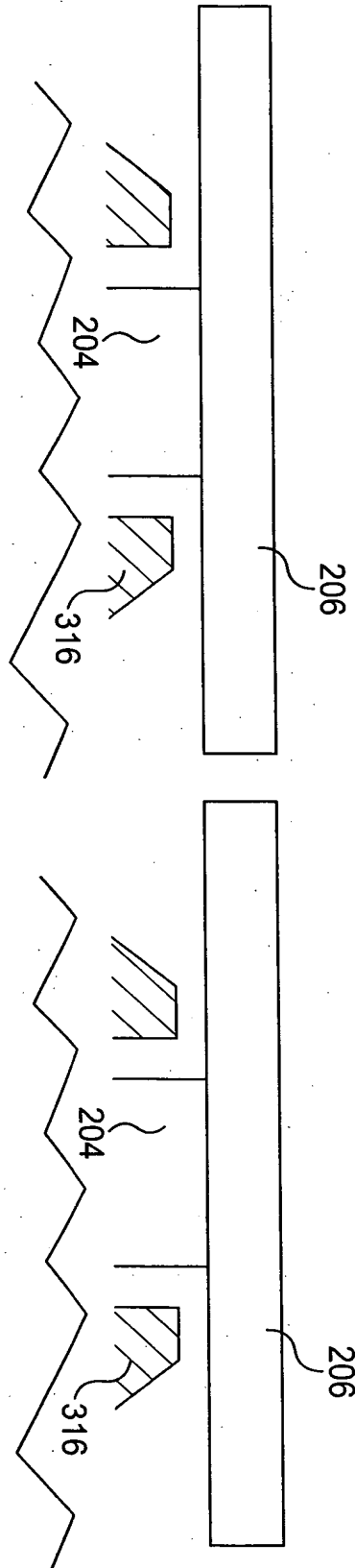
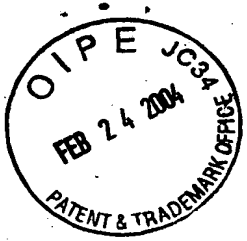


FIG. 9a

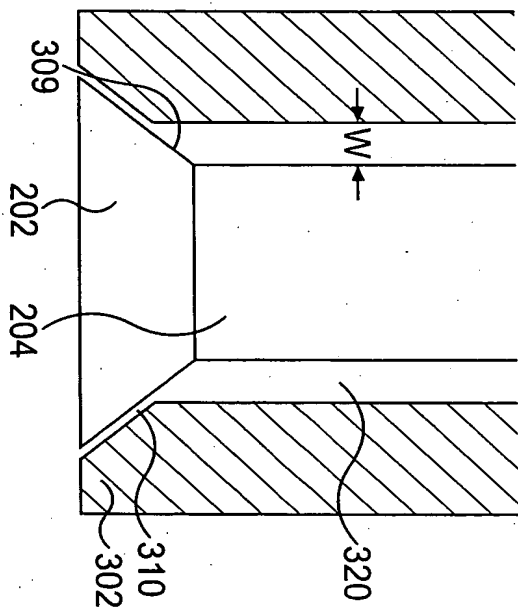
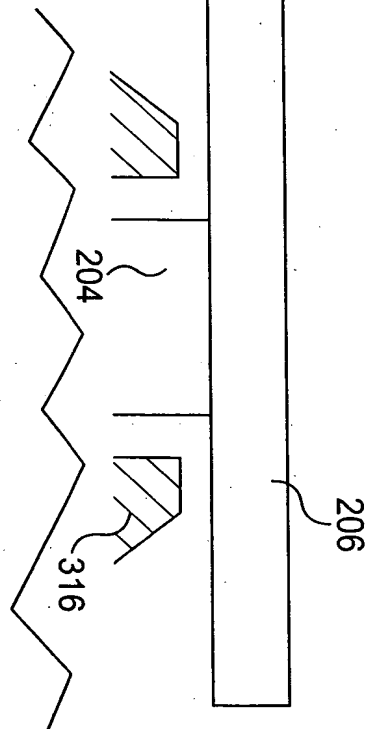


FIG. 9b

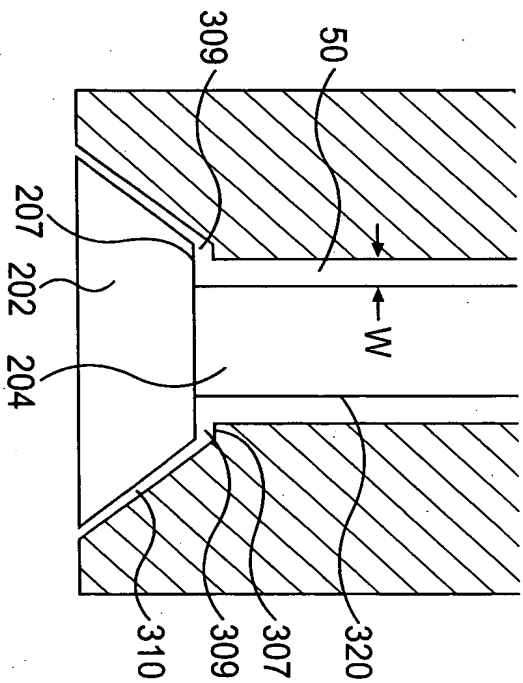
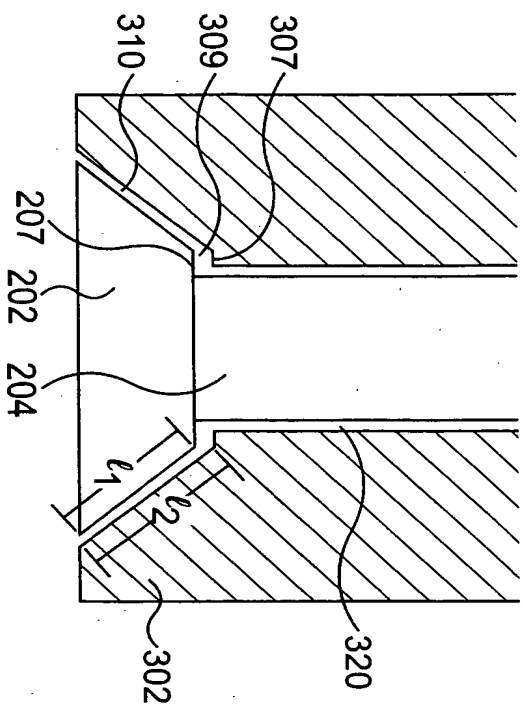
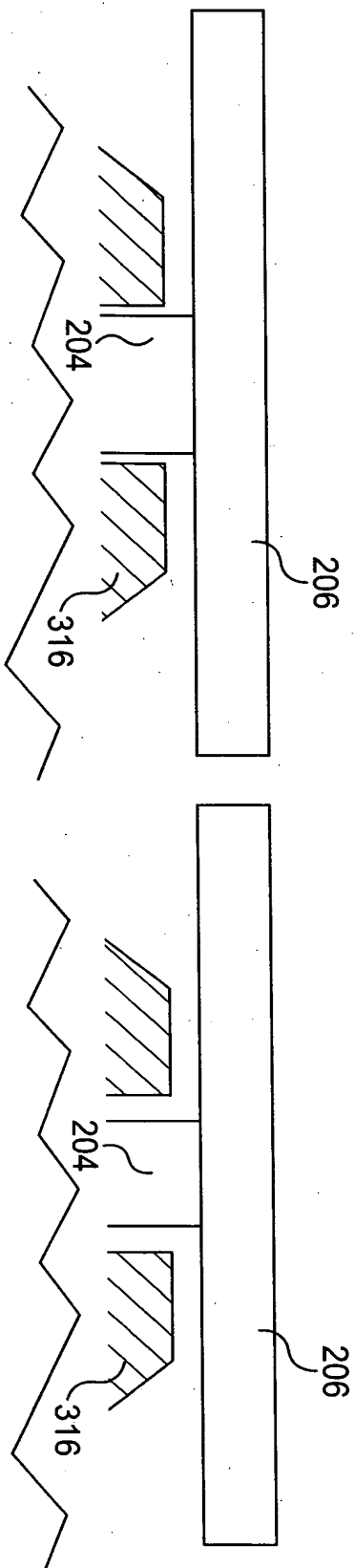
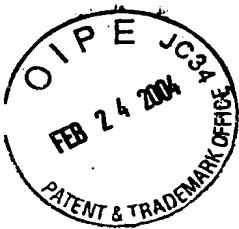


FIG. 9c

FIG. 9d

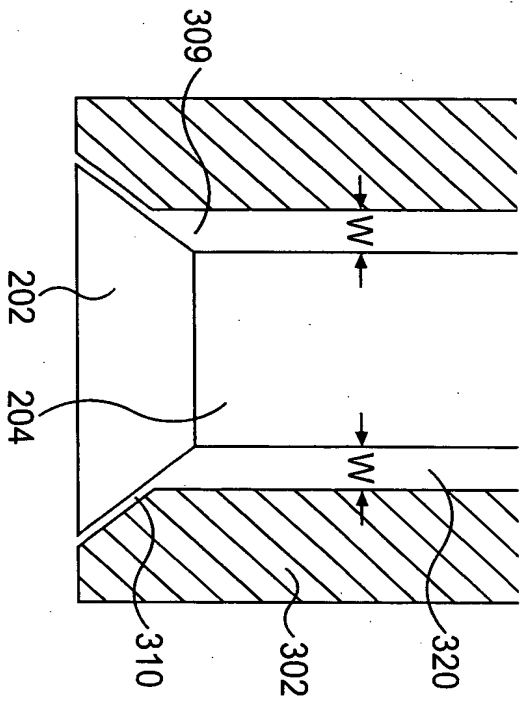
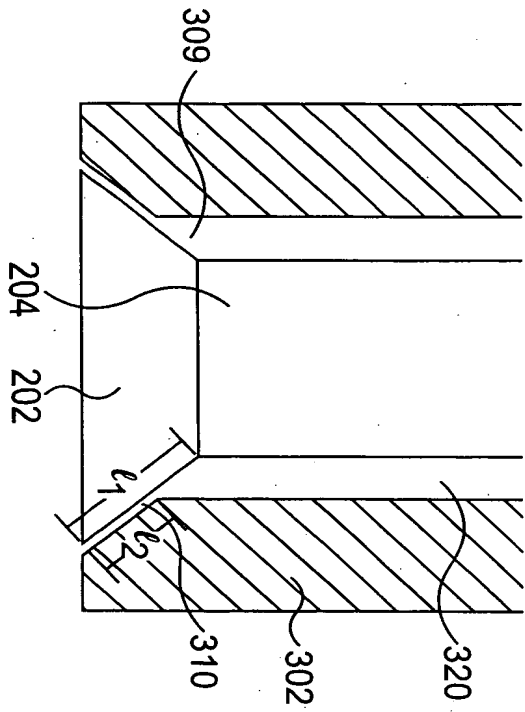
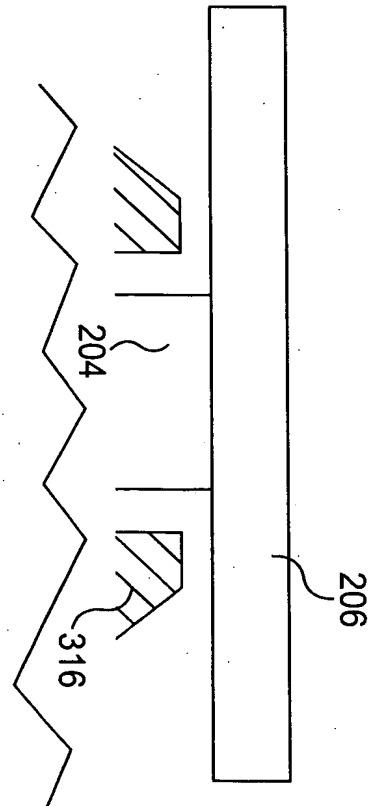
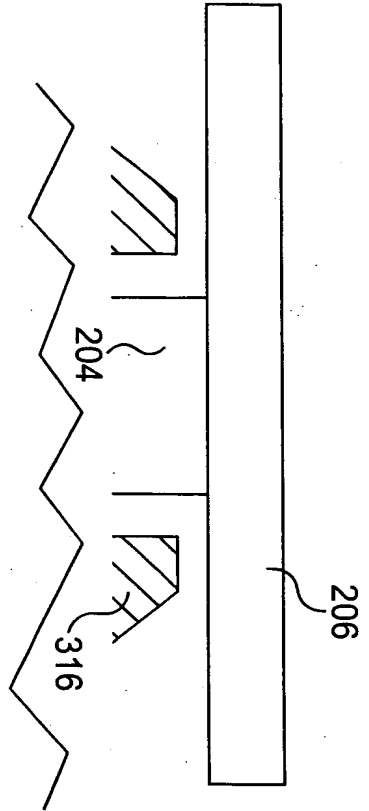
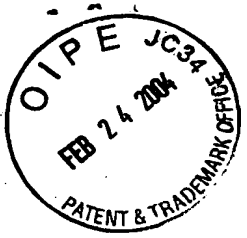


FIG. 10a

FIG. 10b